

Preliminary results on LGAD

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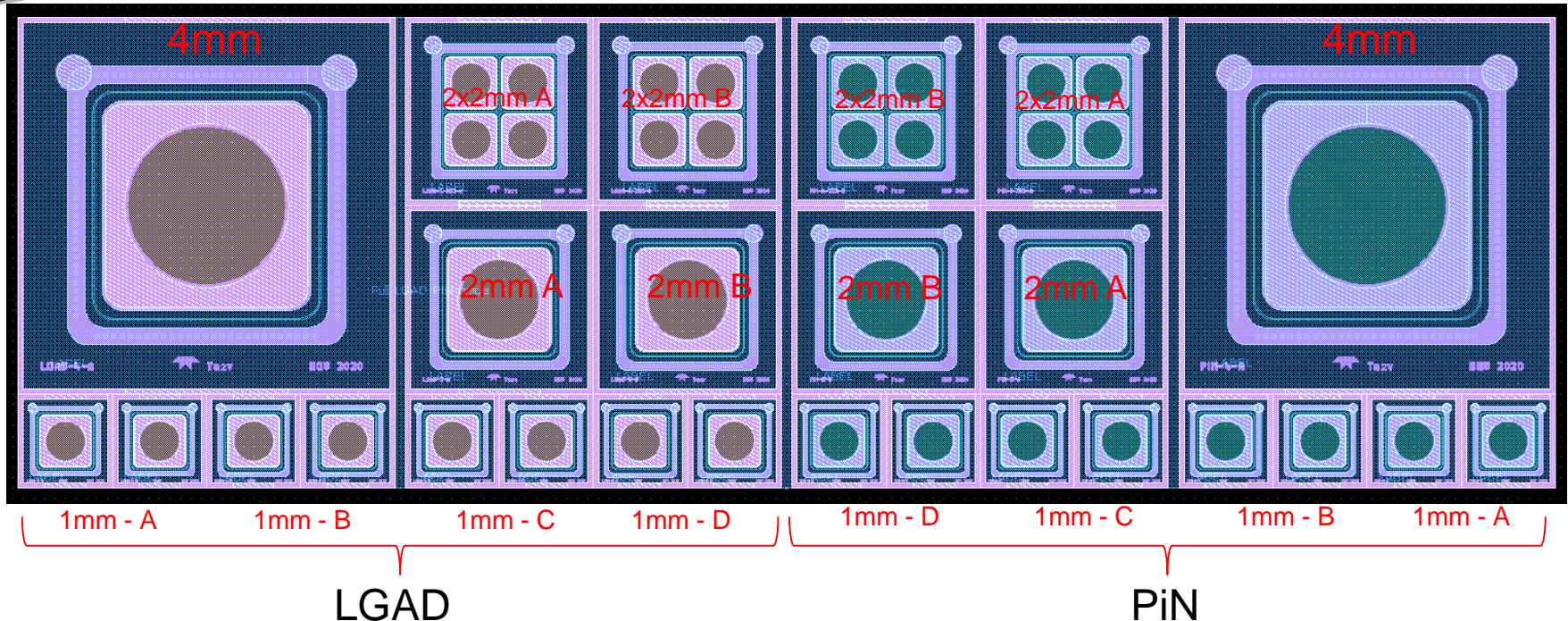


Overview

- LGAD project description and goals
- design simulations
- preliminary results
- next steps

LGAD Project description and goals

Field 1



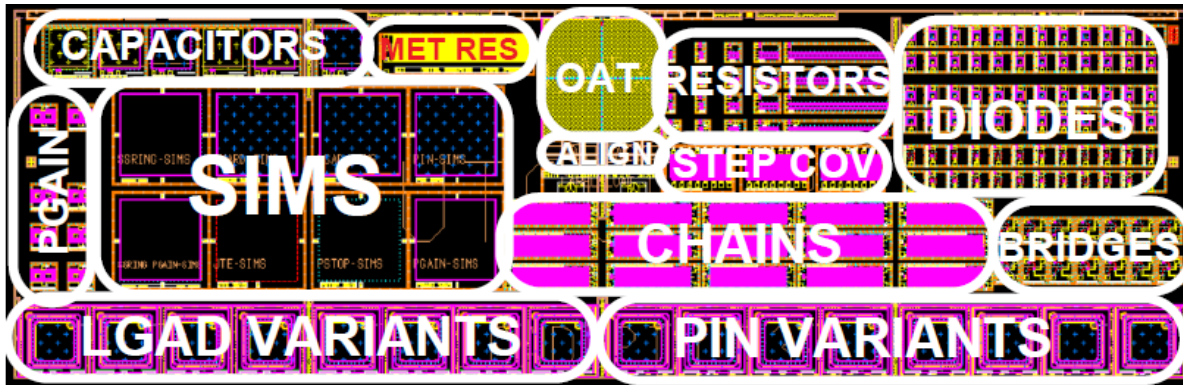
A RAL, University of Oxford, University of Birmingham and Open University project in collaboration with Teledyne e2v foundry for LGAD production

- Three types of cathode size of single cells (4, 2 & 1mm) and one of 2 x 2 array of 1mm cells. Up to four different cell layout flavors (A, B, C, D) are implemented with different distances of guard ring to the cathode
- LGAD and PiN diodes share the same layouts, only difference being the presence or not of the gain layer

LGAD Project description and goals



Field 2



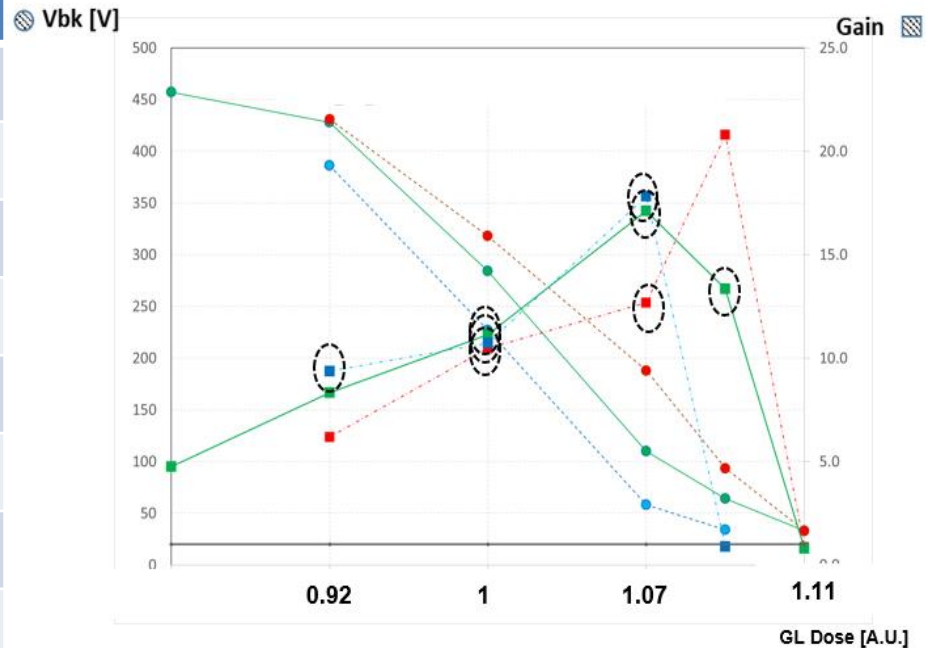
Field 3

- Additional devices are available on each wafer, which has 3 fields, to investigate various effects, including separate biasing of P-stop, retraction of gain layer from JTE contact, further extension or reduction of metal cathode over JTE
- Capacitors, diodes and resistors available too

LGAD Project description and goals

Wafer #	GL dose	GL energy	GL type
1	1	1	Boron
2	1.07	1	Boron
3	0.92	1.05	Boron
4	1	1.05	Boron
5	1.07	1.05	Boron
6	1.15	1.05	Boron
7	1	1.11	Boron
8	1.07	1.11	Boron

Table 1: devices variants

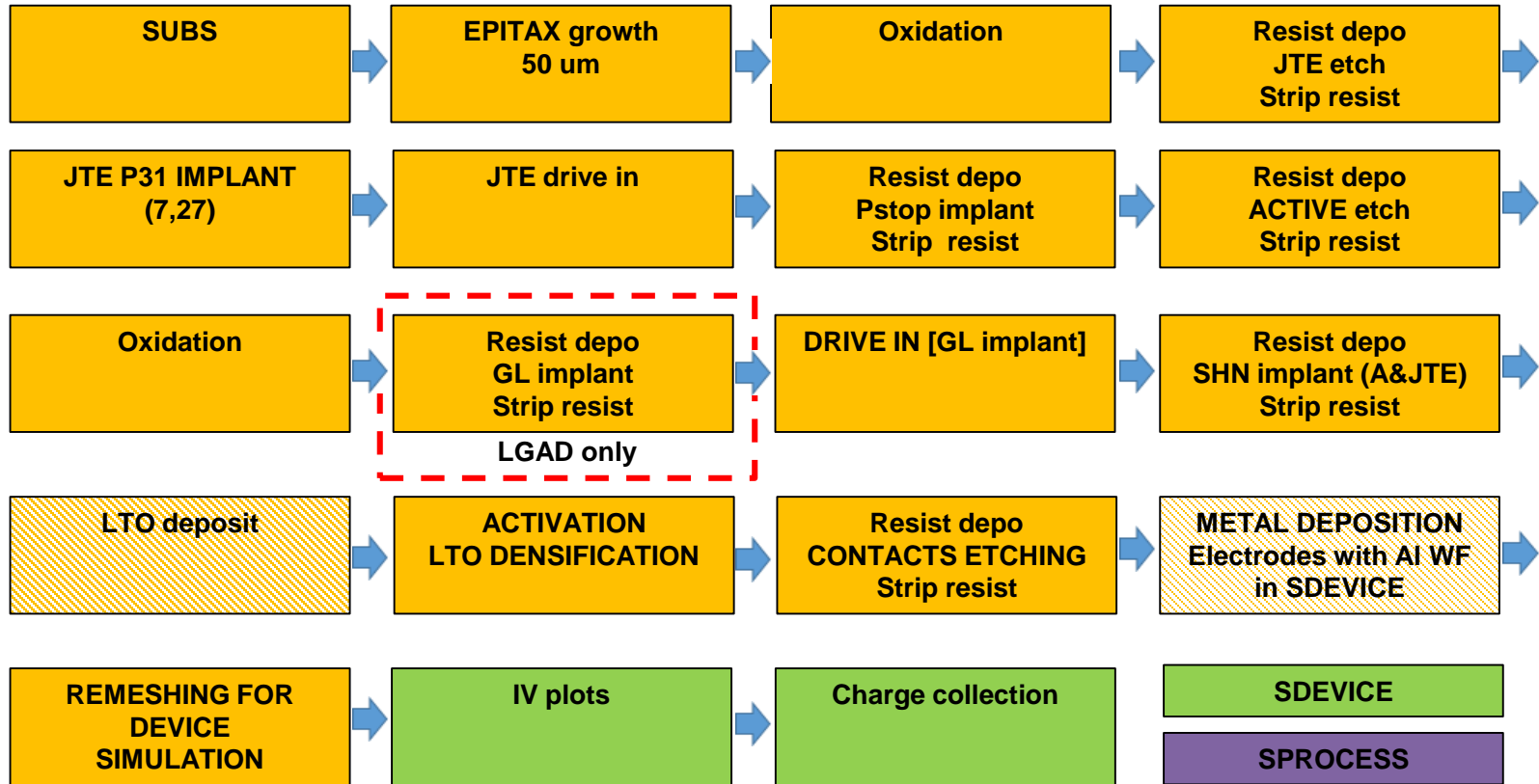


TCAD summary – Gain vs. Dose (E)

- Eight 6” wafers of 50 μ m thick HR P- epi layer
- Different gain layer implant doses and energy to sample gain region according to TCAD simulations

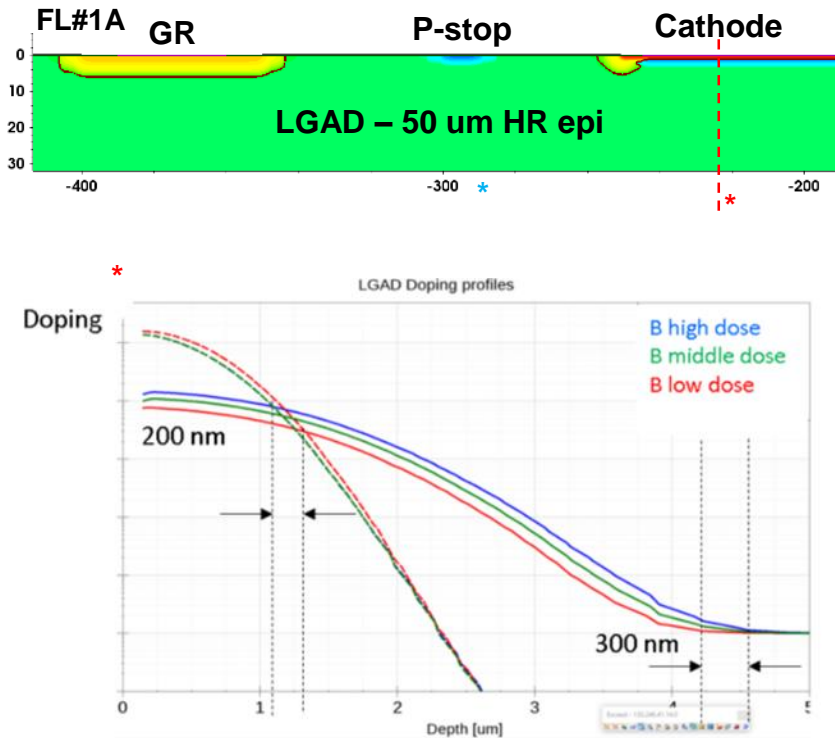
TCAD simulations

SPROCESS
2D process flowchart

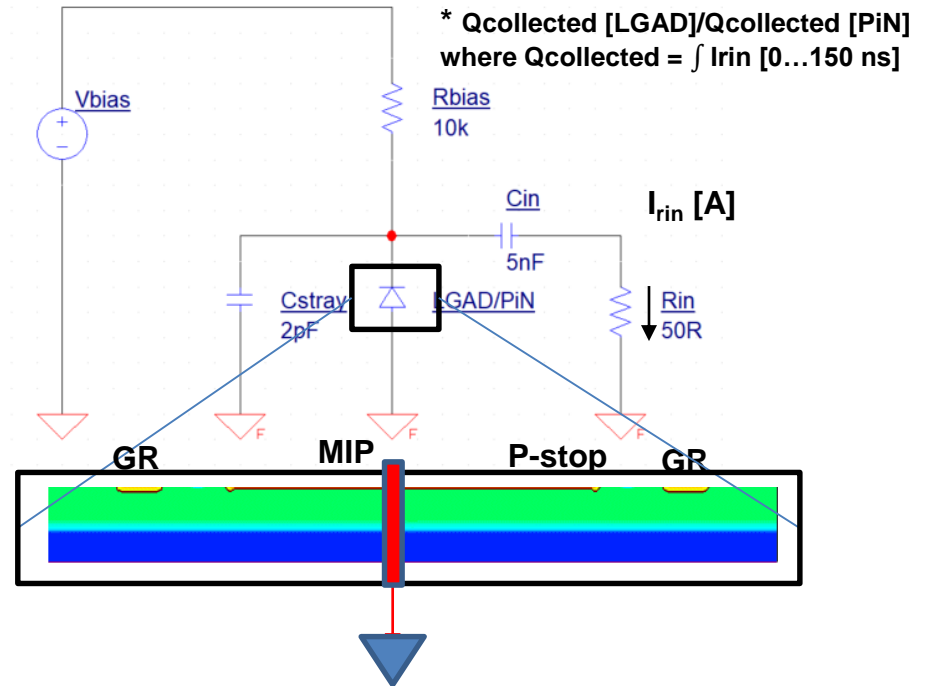


- Full process simulation implemented for LGAD and PiN

TCAD simulations



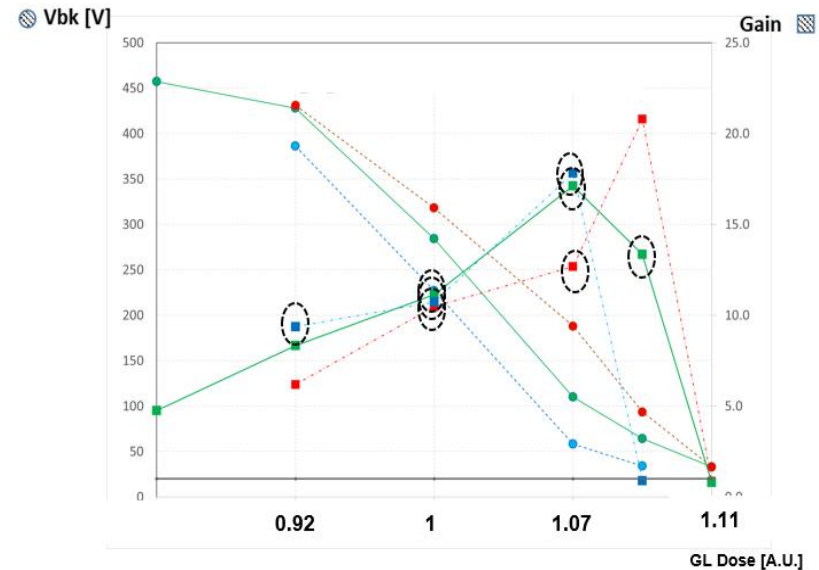
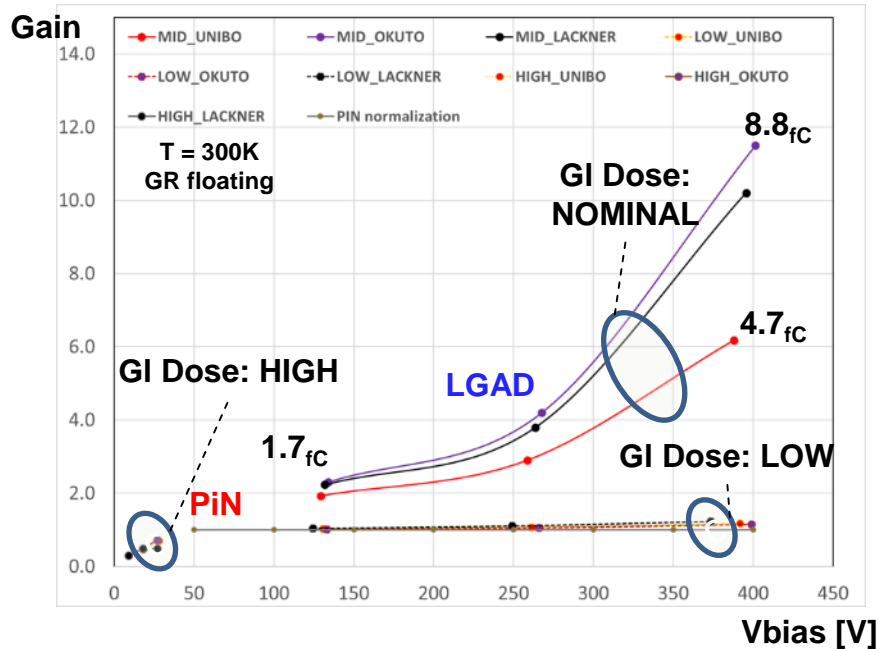
- Extension of GL changes by around 0.5 μm in going from LOW DOSE to MAX DOSE



Electrical simulation setup, common to PiN and LGAD, with RC network

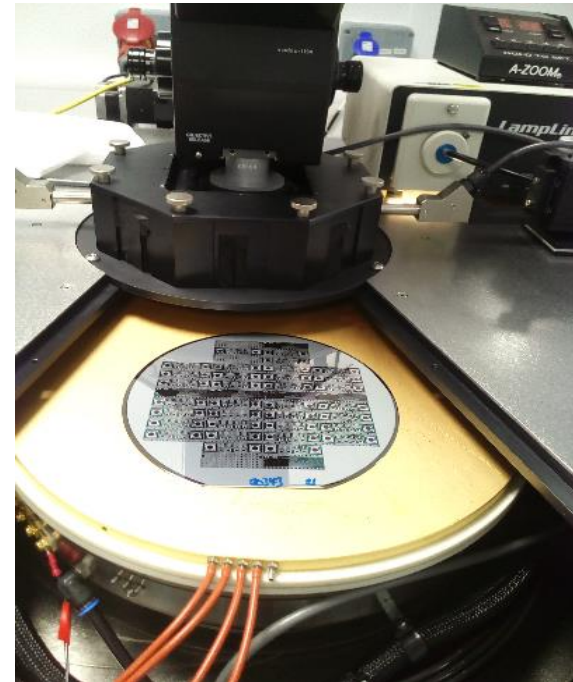
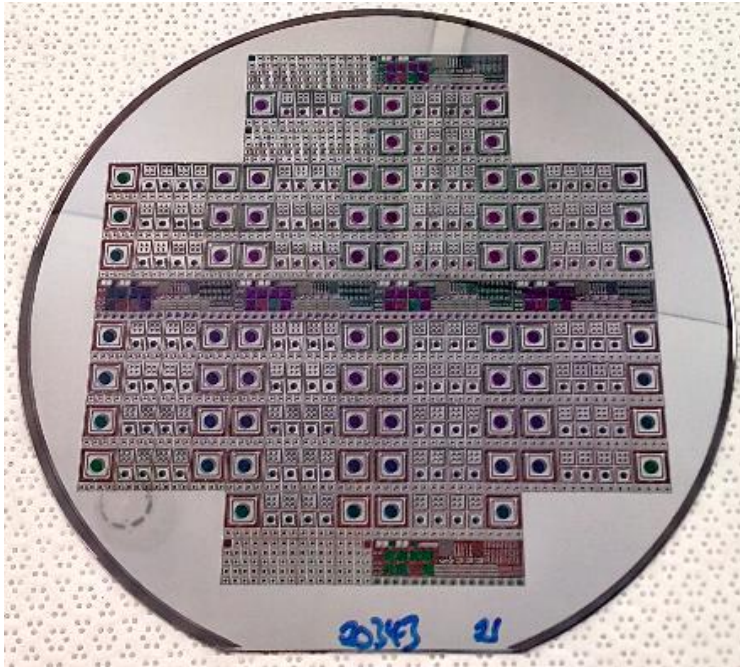
- IV plots
- Bulk radiation damage not included in this iteration, but $\text{SiO}_2\text{-Si}$ interface traps implemented
- CCE for vertical **MIP hit (80 e/h/um)** through centre
- * with no SRH $Q_{\text{coll}} \sim Q_{\text{inj}} \pm 0.1\%$

TCAD simulations



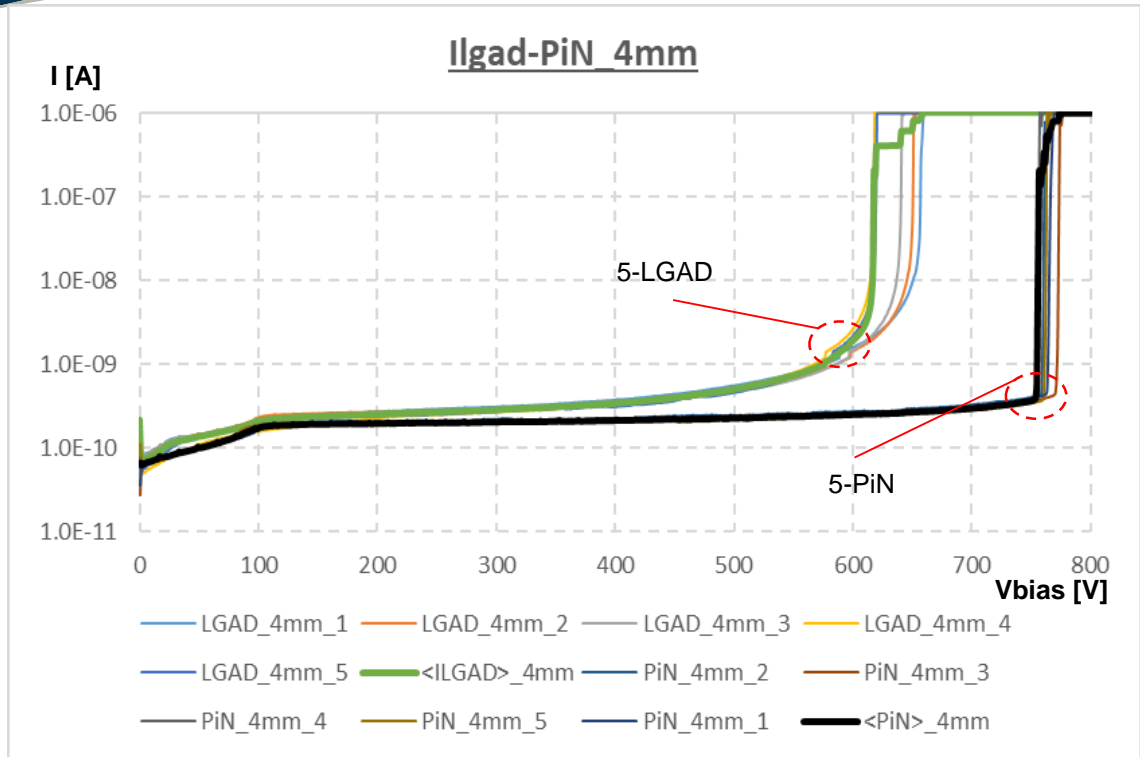
- Gain is defined as ratio of LGAD/PIN collected charge for a 50 ns transient and normalized to 0.3,0.6,0.9 BV
- Each LGAD gain curve is normalized w.r.t. PIN that uses the same Impact Ionization model (3 models used: Unibo, Okuto, Lackner)
- A gain of > 10 is predicted for 2/3 I2 models used for the MIDDLE dose
- Design based on Impact ionization models predicting lowest gain (UniBo)

LGAD Project description and goals

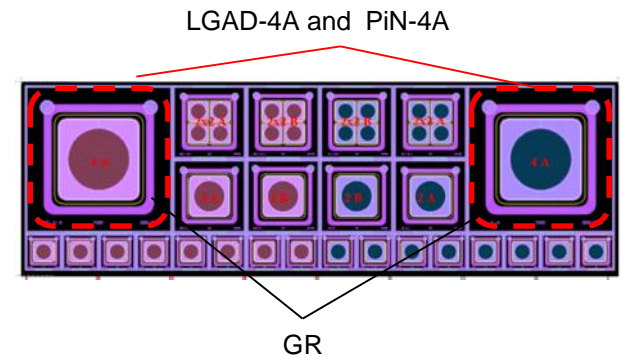
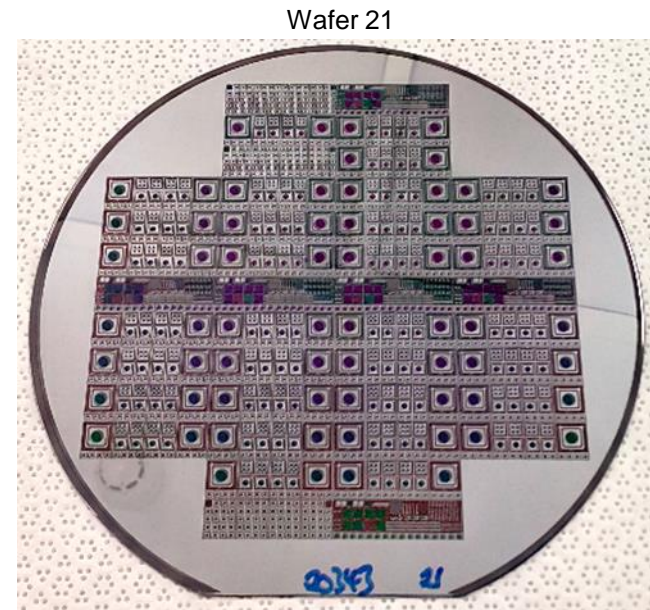


- Fabrication completed November 2020
- First wafer currently being tested at OPMD, Oxford and Birmingham

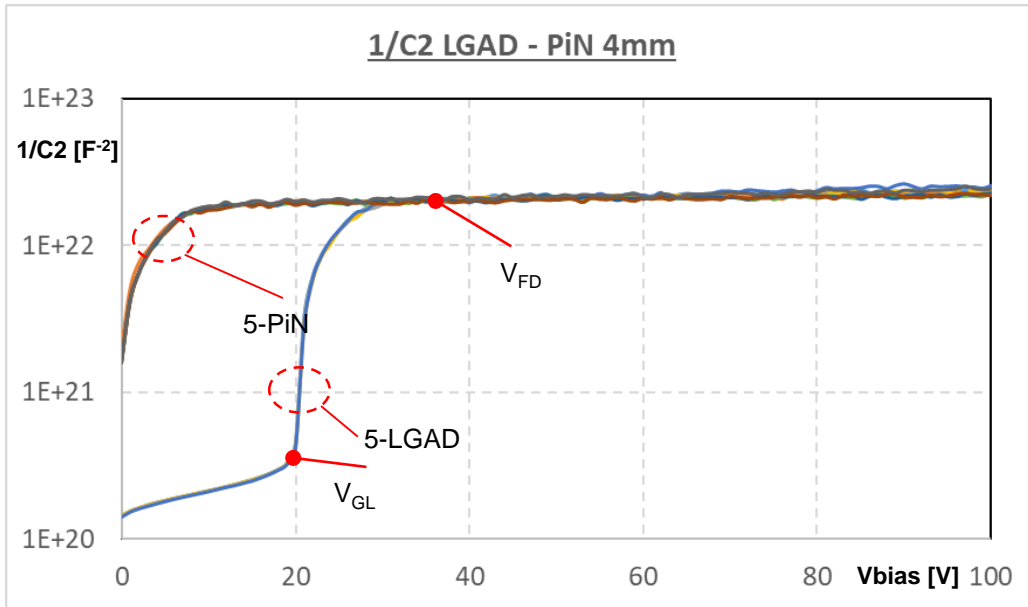
LGAD/PiN IV tests - 4mm



- IV plots of 5 LGAD-4A and 5 PiN-4A devices on WF 21 (E=1,D=1)
- GR floating, T = 21C

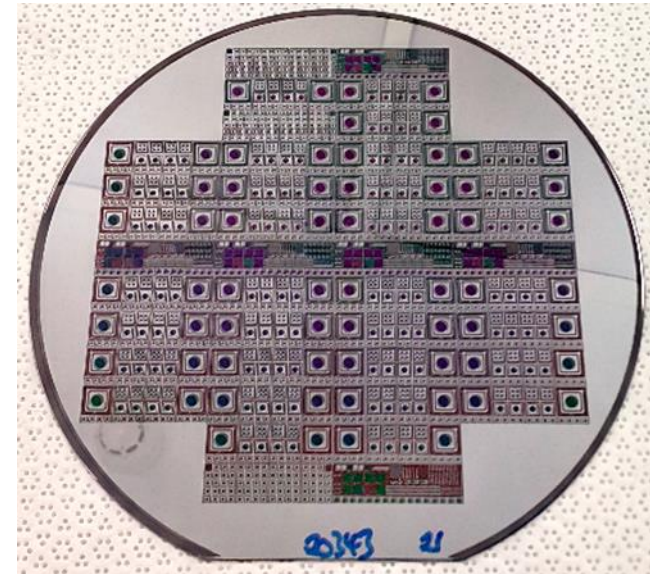


LGAD/PiN CV test - 4mm

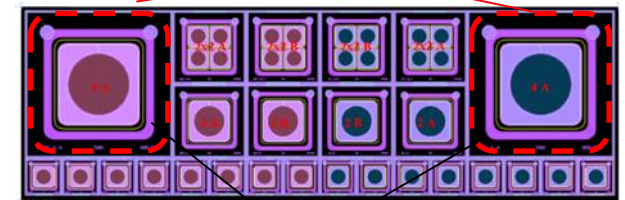


- CV plots of 5 LGAD-4A and 5 PiN-4A devices on WF 21 (E=1,D=1)
- F = 100kHz, AC = 35 mV
- GR floating, T=21C
- GL depletion voltage ~ 20 V, Vfd ~ 32 V

Wafer 21



LGAD-4A and PiN-4A



GR

Summary and next steps

- A RAL, University of Oxford, University of Birmingham and Open University project in collaboration with Teledyne e2v foundry has produced the first batch of LGAD devices
- First fabricated samples available November 2020
- Eight 6" 50um thick p-epi wafers processed with different levels of dose and energy of implanted GL
- First wafer currently being IV-CV tested at Oxford and Birmingham. Laser dicing on it to be performed next

THANK YOU

Acknowledgments

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- **STFC, Teledyne e2v, University of Birmingham
University of Oxford, Open University**

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